

## SURFACE MOUNT GLASS PASSIVATED BRIDGE RECTIFIER

### 0.8A SURFACE MOUNT GLASS PASSIVATED BRIDGE RECTIFIER

#### PINNING

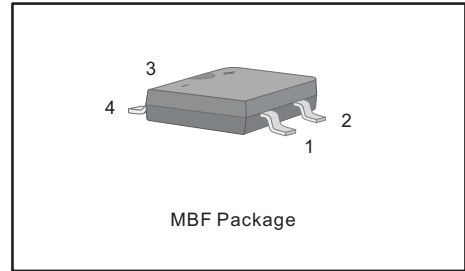
#### FEATURES:

- Glass Passivated Chip Junction
- Reverse Voltage - 100 to 1000 V
- Forward Current - 0.8 A
- Fast reverse recovery time
- Designed for Surface Mount Application

#### MECHANICAL DATA

- Case: MBF
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight: 75mg 0.0026oz

PIN	DESCRIPTION
1	Input Pin ( ~ )
2	Input Pin ( ~ )
3	Output Anode ( + )
4	Output Cathode ( - )



#### Maximum Ratings and Electrical characteristics

Ratings at 25 °C ambient temperature unless otherwise specified.

Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20 %.

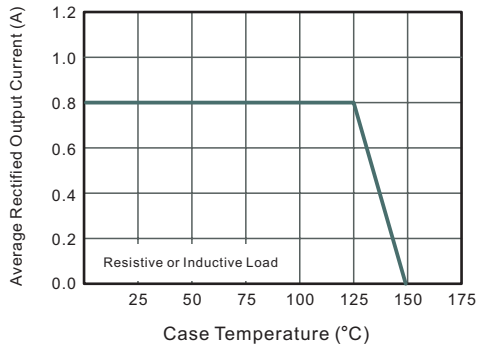
Parameter	Symbols	FMB1F	FMB2F	FMB4F	FMB6F	FMB8F	FMB10F	Units
Maximum Repetitive Peak Reverse Voltage	$V_{RRM}$	100	200	400	600	800	1000	V
Maximum RMS voltage	$V_{RMS}$	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	$V_{DC}$	100	200	400	600	800	1000	V
Average Rectified Output Current at $T_c = 125\text{ }^\circ\text{C}$	$I_O$	0.8						A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	$I_{FSM}$	30						A
Maximum Forward Voltage at 0.8 A	$V_F$	1.3						V
Maximum DC Reverse Current $T_a = 25\text{ }^\circ\text{C}$ at Rated DC Blocking Voltage $T_a = 125\text{ }^\circ\text{C}$	$I_R$	5.0 50						$\mu\text{A}$
Typical Junction Capacitance ( Note1 )	$C_j$	12						pF
Maximum Reverse Recovery Time ( Note2 )	$t_{rr}$ $t_{rr(TYP.)}$	500 300						ns
Typical Thermal Resistance ( Note3 )	$R_{\theta JA}$ $R_{\theta JC}$	90 30						$^\circ\text{C/W}$
Operating and Storage Temperature Range	$T_j, T_{stg}$	-55 ~ +150						$^\circ\text{C}$

Note: 1. Measured at 1MHz and applied reverse voltage of 4 V D.C.

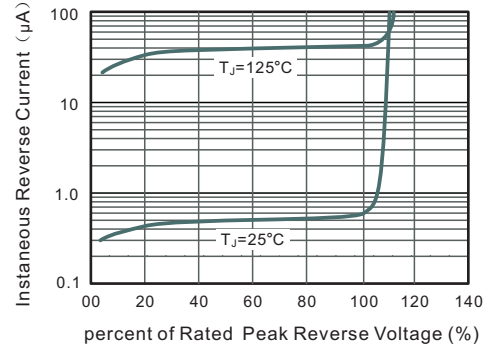
2. Measured with  $I_F = 0.5\text{ A}$ ,  $I_R = 1\text{ A}$ ,  $I_{rr} = 0.25\text{ A}$ .

3. Mounted on glass epoxy PC board with  $4 \times 1.5'' \times 1.5''$  ( 3.81 $\times$ 3.81 cm ) copper pad.

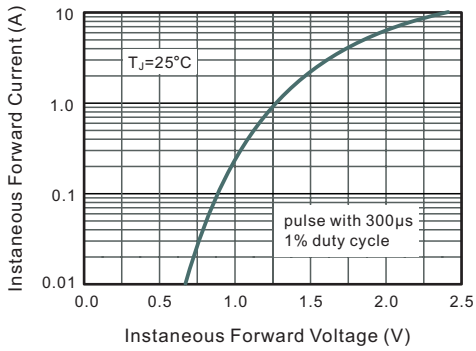
**Fig.1 Average Rectified Output Current Derating Curve**



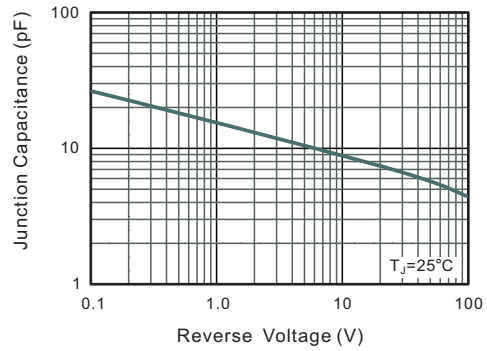
**Fig.2 Typical Reverse Characteristics**



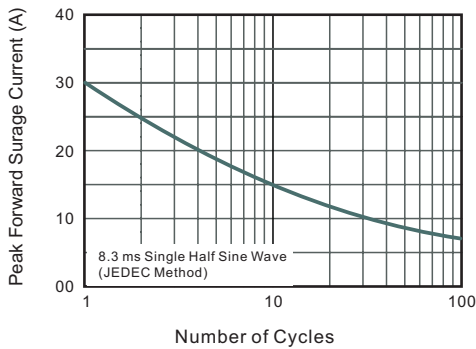
**Fig.3 Typical Instantaneous Forward Characteristics**



**Fig.4 Typical Junction Capacitance**



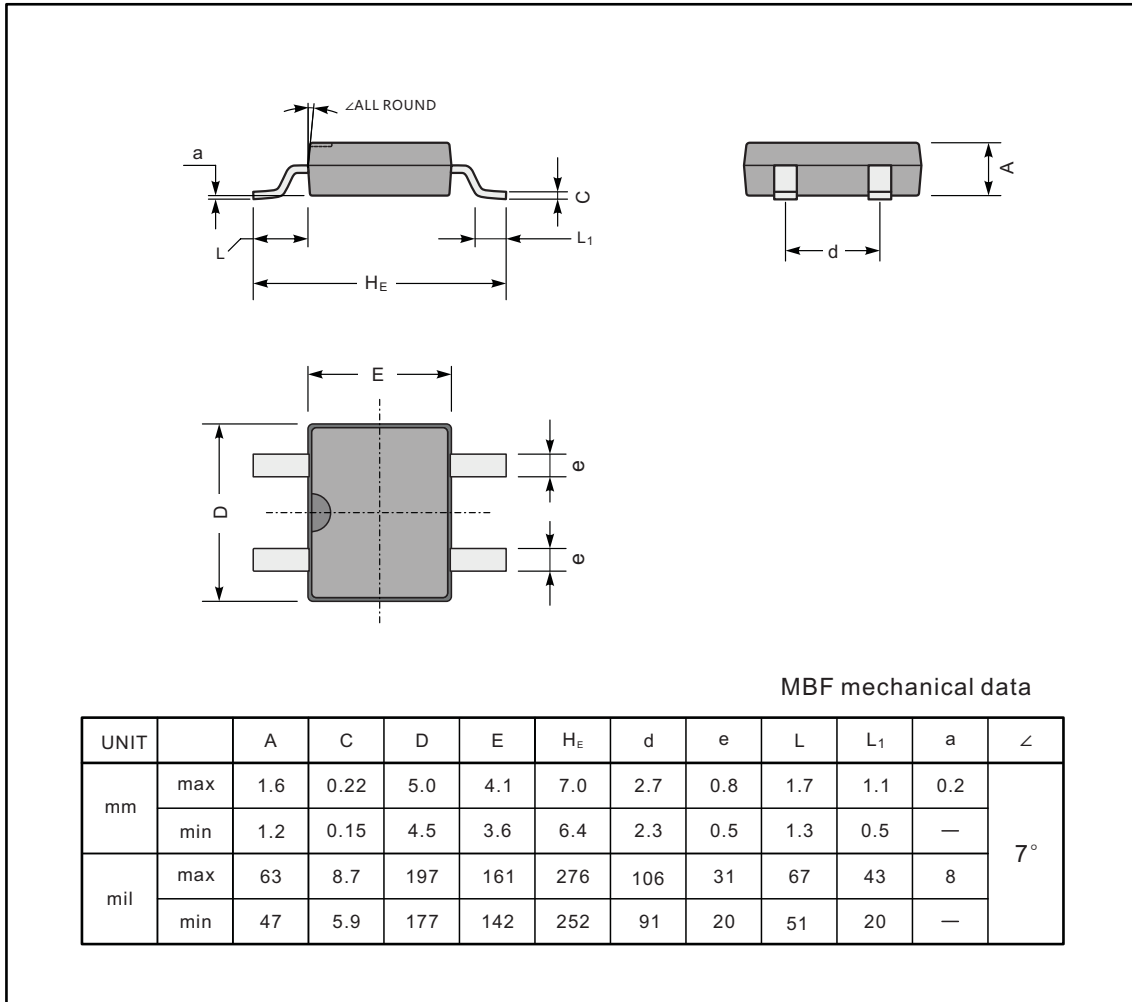
**Fig.5 Maximum Non-Repetitive Peak Forward Surge Current**



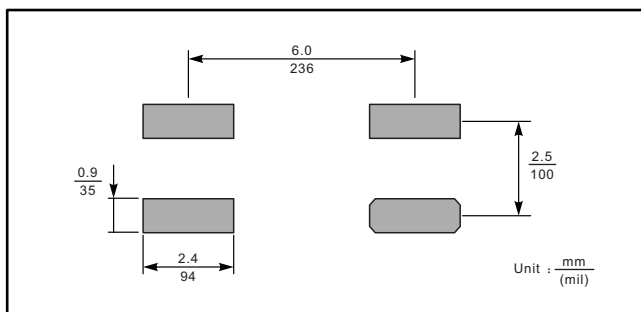
### PACKAGE OUTLINE

Plastic surface mounted package; 4 leads

MBF



### The recommended mounting pad size



### Marking

Type number	Marking code
FMB1F	FMB1F
FMB2F	FMB2F
FMB4F	FMB4F
FMB6F	FMB6F
FMB8F	FMB8F
FMB10F	FMB10F

